

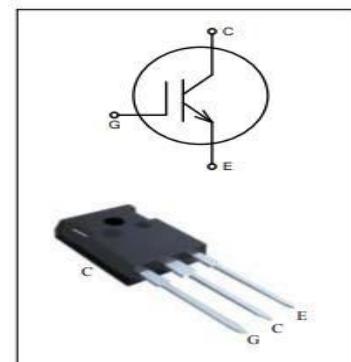


CHONGQING CLOUDCHILD TECHNOLOGY CO.,LTD

TO247-3 Plastic-Encapsulate IGBT

CCG40Q120KAH IGBT in Trench FS Technology

$V_{(BR)CES}$	VCEsat		IC	
1200 V	Tvj=25°C	1.80V@40A	Tvj=25°C	80A
	Tvj=150°C	2.15V@40A	Tvj=100°C	40A



Features:

- 1200V Trench field-stop technology
- Low conduction and switching losses
- Positive temperature coefficient of forward voltage
- Short Circuit withstand time-10μs
- AEC Q101 qualified

Applications:

- Automobile PTC
- Short-Circuit Protector

Key Performance and Package Parameters

Type	VCE	IC	VCEsat, Tvj=25° C	Tvjmax	Marking	Package
CCG40Q120KAH	1200V	40A	1.80V	175° C	CCG40Q120KAH	PG-T0247-3



CHONGQING CLOUDCHILD TECHNOLOGY CO.,LTD

TO247-3 Plastic-Encapsulate IGBT

Maximum Ratings

For optimum lifetime and reliability, cloudchild recommends operating conditions that do not exceed 80% of the maximum ratings stated in this datasheet.

Parameter	Symbol	Value	Unit
Collector-emitter voltage	V_{CE}	1200	V
DC collector current, limited by T_{vjmax}	I_C	80.0 40.0	A
$T_C = 25^\circ\text{C}$			
$T_C = 100^\circ\text{C}$			
Pulsed collector current, t_p limited by T_{vjmax}	I_{Cpuls}	160.0	A
Gate-emitter voltage	V_{GE}	± 20	V
Short circuit withstand time $V_{GE} = 15.0\text{V}$, $V_{CC} \leq 600\text{V}$	t_{SC}	10	μs
Allowed number of short circuits < 1000			
Time between short circuits: $\geq 1.0\text{s}$			
$T_{vj} = 175^\circ\text{C}$			
Power dissipation $T_C = 25^\circ\text{C}$	P_{tot}	484.0	W
Operating junction temperature	T_{vj}	-40...+175	$^\circ\text{C}$
Storage temperature	T_{stg}	-55...+175	$^\circ\text{C}$
Soldering temperature, wave soldering 1.6mm (0.063in.) from case for 10s		260	$^\circ\text{C}$
Mounting torque, M3 screw Maximum of mounting processes: 3	M	0.6	Nm

Thermal Resistance

Parameter Characteristic	Symbol	Conditions	Max. Value	Unit
IGBT thermal resistance, junction - case	$R_{th(j-c)}$	/	0.31	K/W
Thermal resistance junction - ambient	$R_{th(j-a)}$	/	42	K/W



CHONGQING CLOUDCHILD TECHNOLOGY CO.,LTD

TO247-3 Plastic-Encapsulate IGBT

Electrical Characteristic, at $T_{vj} = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Static Characteristic						
Collector-emitter breakdown voltage	$V_{(BR)CE}$	$V_{GE} = 0\text{V}, I_C = 1\text{mA}$	1200	-	-	V
Collector-emitter saturation voltage	V_{CESat}	$V_{GE} = 15.0\text{V}, I_C = 40.0\text{A}$ $T_{vj} = 25^\circ\text{C}$ $T_{vj} = 150^\circ\text{C}$	-	1.80	2.10	V
Gate-emitter threshold voltage	$V_{GE(\text{th})}$	$I_C = 1.60\text{mA}, V_{CE} = V_{GE}$	5.5	5.8	6.5	V
Zero gate voltage collector current	I_{CES}	$V_{CE} = 1200\text{V}, V_{GE} = 0\text{V}$ $T_{vj} = 25^\circ\text{C}$ $T_{vj} = 150^\circ\text{C}$	-	-	100.0	μA
Gate-emitter leakage current	I_{GES}	$V_{CE} = 0\text{V}, V_{GE} = 20\text{V}$	-100	-	100	nA
Transconductance	g_{fs}	$V_{CE} = 20\text{V}, I_C = 15.0\text{A}$	-	20.0	-	S

Electrical Characteristic, at $T_{vj} = 25^\circ\text{C}$, unless otherwise specified

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Dynamic Characteristic						
Input capacitance	C_{ies}		-	2720	-	
Output capacitance	C_{oes}	$V_{CE} = 25\text{V}, V_{GE} = 0\text{V}, f = 1\text{MHz}$	-	200	-	pF
Reverse transfer capacitance	C_{res}		-	135	-	
Gate charge	Q_G	$V_{CC} = 960\text{V}, I_C = 40.0\text{A}, V_{GE} = 15\text{V}$	-	230	-	nC
Internal emitter inductance measured 5mm from case	L_E		-	12.0	-	nH



TO247-3 Plastic-Encapsulate IGBT

Switching Characteristic, Inductive Load

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
IGBT Characteristic, at $T_{vj} = 25^\circ\text{C}$						
Turn-on delay time	$t_{d(on)}$	$T_{vj} = 25^\circ\text{C}$, $V_{CC} = 600\text{V}$, $I_C = 40.0\text{A}$, $V_{GE} = -7.5/15.0\text{V}$,	-	30	-	ns
Rise time	t_r	$R_{G(on)} = 10.0\Omega$, $R_{G(off)} = 10.0\Omega$, $L\sigma = 70\text{nH}$, $C\sigma = 67\text{pF}$	-	40	-	ns
Turn-off delay time	$t_{d(off)}$		-	290	-	ns
Fall time	t_f		-	90	-	ns
Turn-on energy	E_{on}		-	3.55	-	mJ
Turn-off energy	E_{off}		-	1.55	-	mJ
Total switching energy	E_{ts}		-	5.15	-	mJ

Switching Characteristic, Inductive Load

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
IGBT Characteristic, at $T_{vj} = 150^\circ\text{C}$						
Turn-on delay time	$t_{d(on)}$	$T_{vj} = 150^\circ\text{C}$, $V_{CC} = 600\text{V}$, $I_C = 40.0\text{A}$, $V_{GE} = -7.5/15.0\text{V}$,	-	56	-	ns
Rise time	t_r	$R_{G(on)} = 10.0\Omega$, $R_{G(off)} = 10.0\Omega$, $L\sigma = 70\text{nH}$, $C\sigma = 67\text{pF}$	-	90	-	ns
Turn-off delay time	$t_{d(off)}$		-	423	-	ns
Fall time	t_f		-	152	-	ns
Turn-on energy	E_{on}		-	5.26	-	mJ
Turn-off energy	E_{off}		-	2.68	-	mJ
Total switching energy	E_{ts}		-	8.27	-	mJ



TO247-3 Plastic-Encapsulate IGBT

Typical Characteristic Curve

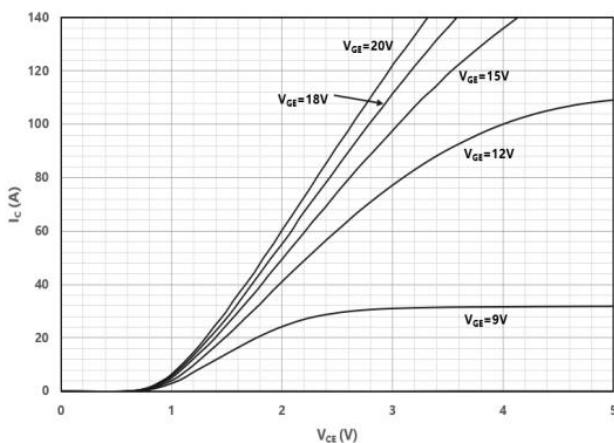
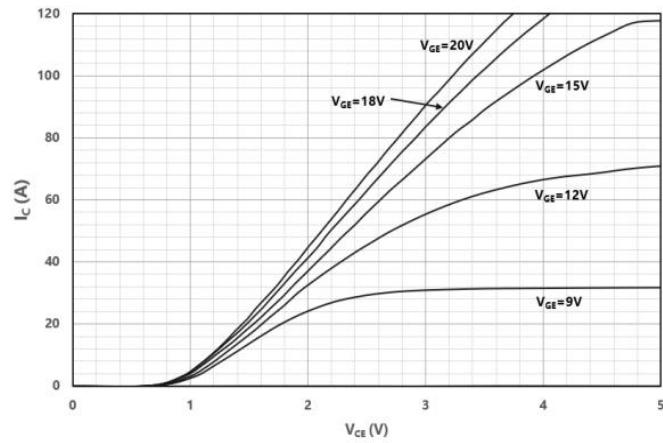
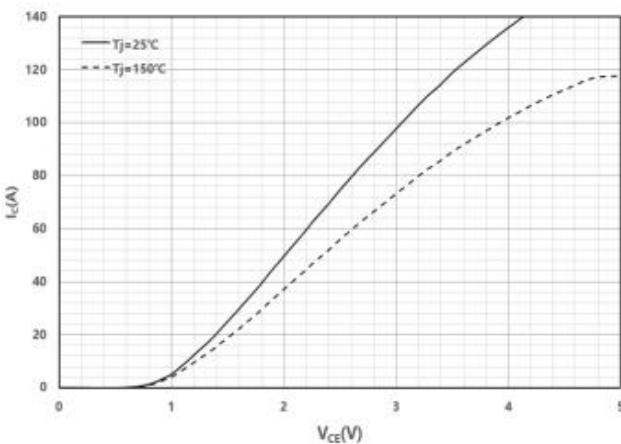
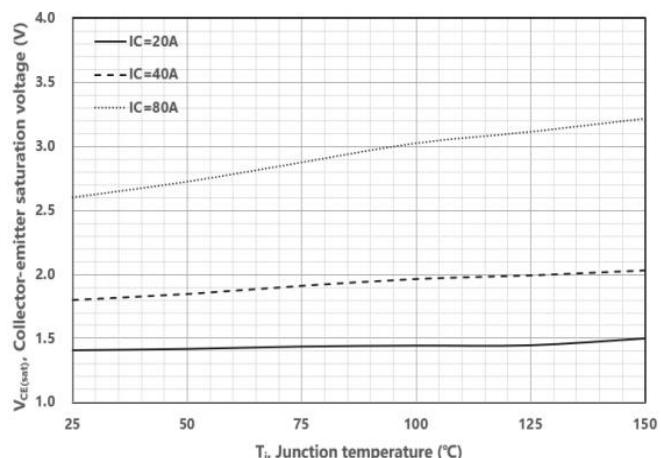
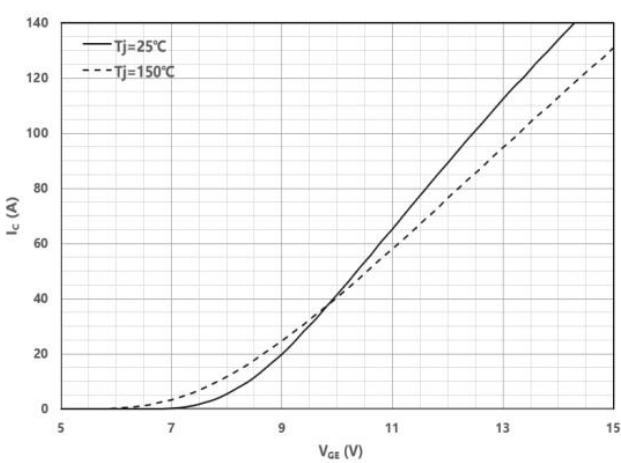
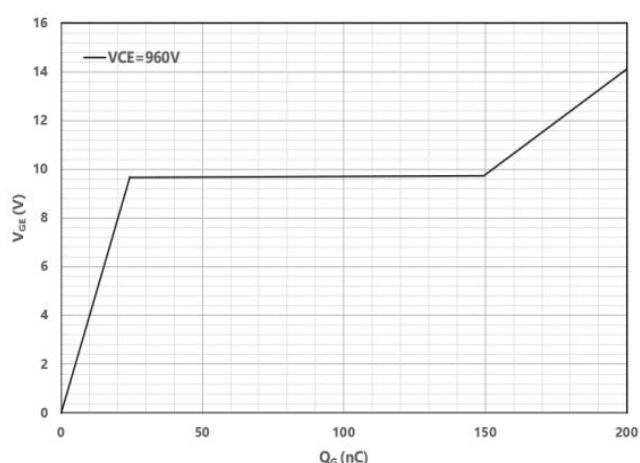
Fig.1 Typical Output Characteristic ($T_j=25^\circ\text{C}$)Fig.2 Typical Output Characteristic ($T_j=150^\circ\text{C}$)Fig.3 Typical Saturation Voltage Characteristic ($V_{GE}=15\text{V}$)Fig.4 Typical Saturation Voltage Temperature Characteristic ($V_{GE}=15\text{V}, T_j=25^\circ\text{C}$)Fig.5 Typical Transfer Characteristic ($V_{CE}=20\text{V}$)

Fig.6 Typical Gate Charge



TO247-3 Plastic-Encapsulate IGBT

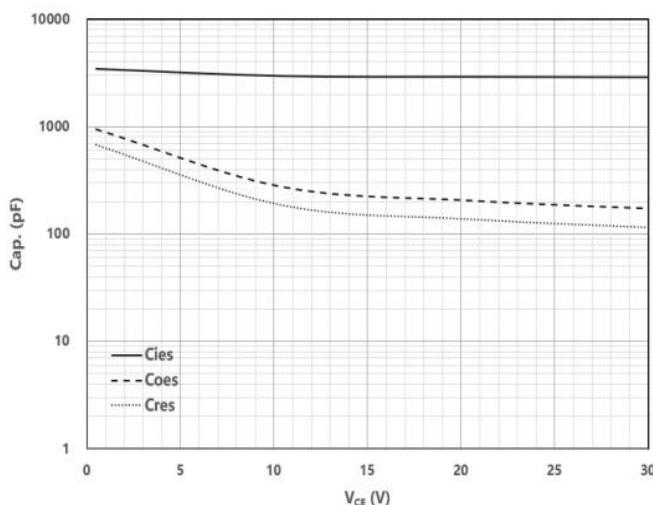


Fig.7 Typical Capacitance Characteristic

($V_{GE}=0V$, $f=1MHz$, $T_j=25^\circ C$)

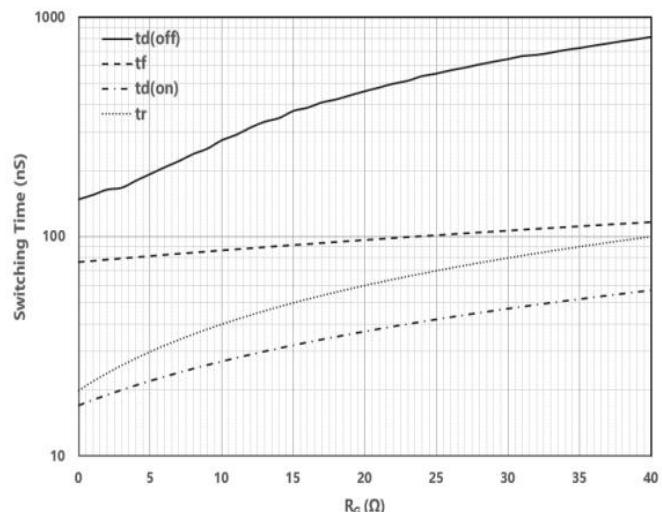


Fig.8 Typical Switching Time vs R_G (Ind. load,

$V_{CE}=600V$, $V_{GE}=15V/0V$, $I_c=40A$, $T_j=25^\circ C$)

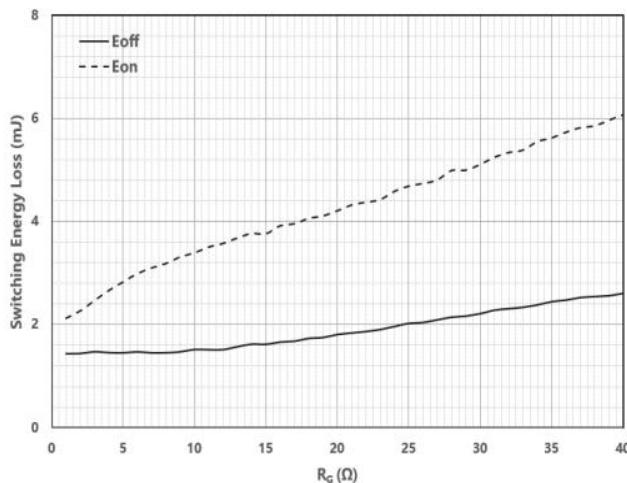


Fig.9 Typical Switching Energy vs R_G

(Ind. load, $V_{CE}=600V$, $V_{GE}=15V/0V$, $I_c=40A$, $T_j=25^\circ C$)

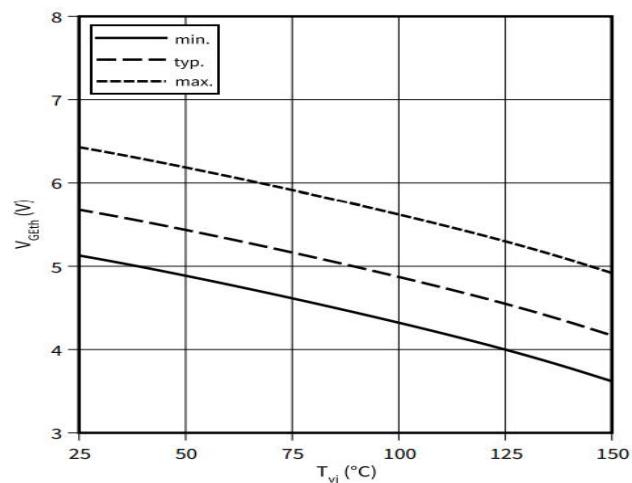


Fig.10 Gate-emitter threshold voltage as a function

of junction temperature, $VGEth = f(T_{vj})$ IC = 0.85 mA

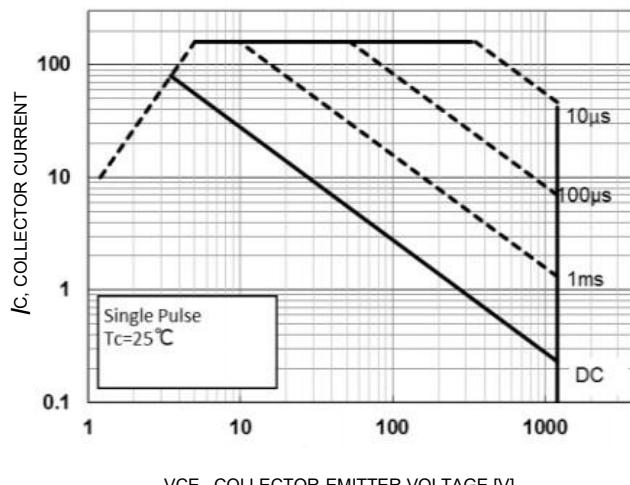


Fig 11. Typical positive safe working area characteristics

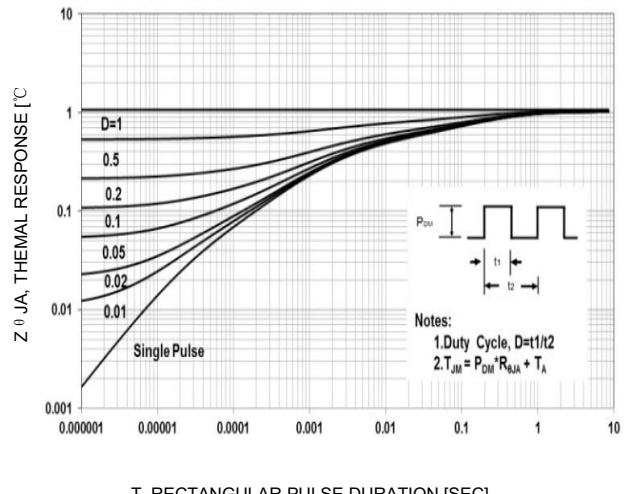


Fig12. Typical transient thermal resistance characteristics



CHONGQING CLOUDCHILD TECHNOLOGY CO.,LTD

TO247-3 Plastic-Encapsulate IGBT

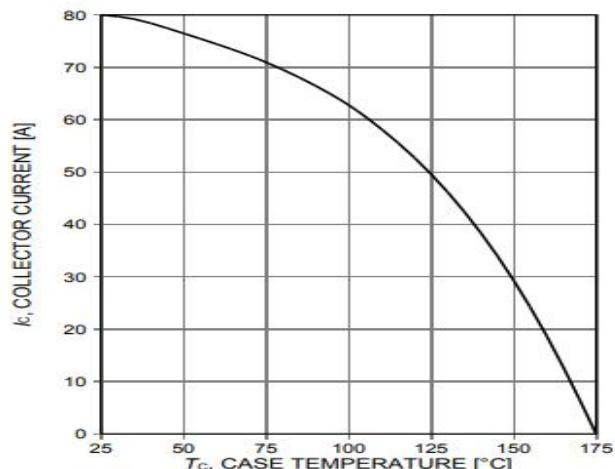


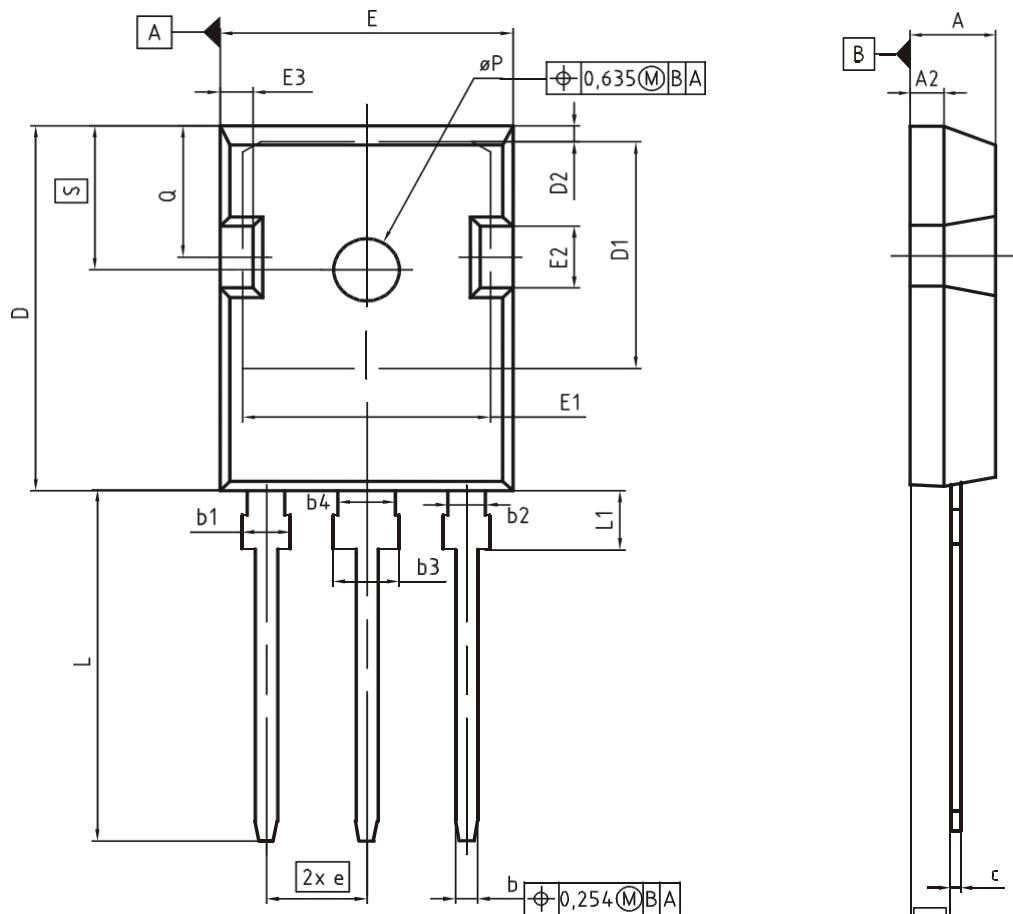
Fig13. Collectorcurrentasfunctionofcasetemperature



CHONGQING CLOUDCHILD TECHNOLOGY CO.,LTD

TO247-3 Plastic-Encapsulate IGBT

PG-TO247-3 Outline Dimensions



DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	4.83	5.21	0.190	0.205
A1	2.27	2.54	0.089	0.100
A2	1.85	2.16	0.073	0.085
b	1.07	1.33	0.042	0.052
b1	1.90	2.41	0.075	0.095
b2	1.90	2.16	0.075	0.085
b3	2.87	3.38	0.113	0.133
b4	2.87	3.13	0.113	0.123
c	0.55	0.68	0.022	0.027
D	20.80	21.10	0.819	0.831
D1	16.25	17.65	0.640	0.695
D2	0.95	1.35	0.037	0.053
E	15.70	16.13	0.618	0.635
E1	13.10	14.15	0.516	0.557
E2	3.68	5.10	0.145	0.201
E3	1.00	2.60	0.039	0.102
e	5.44 (BSC)		0.214 (BSC)	
N	3		3	
L	19.80	20.32	0.780	0.800
L1	4.10	4.47	0.161	0.176
ØP	3.50	3.70	0.138	0.146
Q	5.49	6.00	0.216	0.236
S	6.04	6.30	0.238	0.248

DOCUMENT NO.
Z8B00003327
SCALE
0
0 5 5
7.5mm
EUROPEAN PROJECTION
ISSUE DATE
09-07-2010
REVISION
05

NOTICE

CLOUDCHILD reserves the right to make modifications,enhancements,improvements,corrections or other changes without further notice to any product herein.CLOUDCHILD does not assume any liability arising out of the application or use of any product described herein.